www.ti.com

14-Oct-2025

## **PACKAGING INFORMATION**

Orderable part number	Status	Material type (2)	Package   Pins	Package qty   Carrier	(3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
UCC27200D	Obsolete	Production	SOIC (D)   8	-	-	Call TI	Call TI	-40 to 140	27200
UCC27200DDA	Obsolete	Production	SO PowerPAD (DDA)   8	-	-	Call TI	Call TI	-40 to 140	27200
UCC27200DDAR	Active	Production	SO PowerPAD (DDA)   8	2500   LARGE T&R	Yes	NIPDAU   NIPDAUAG	Level-1-260C-UNLIM	-40 to 150	27200
UCC27200DDAR.A	Active	Production	SO PowerPAD (DDA)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27200
UCC27200DDAR.B	Active	Production	SO PowerPAD (DDA)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27200
UCC27200DR	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27200
UCC27200DR.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27200
UCC27200DR.B	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27200
UCC27200DRG4	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 140	27200
UCC27200DRG4.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 140	27200
UCC27200DRG4.B	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 140	27200
UCC27200DRMR	Active	Production	VSON (DRM)   8	3000   LARGE T&R	Yes	Call TI   Nipdauag   Nipdau	Level-2-260C-1 YEAR	-40 to 150	27200
UCC27200DRMR.A	Active	Production	VSON (DRM)   8	3000   LARGE T&R	Yes	Call TI	Level-2-260C-1 YEAR	-40 to 150	27200
UCC27200DRMR.B	Active	Production	VSON (DRM)   8	3000   LARGE T&R	Yes	Call TI	Level-2-260C-1 YEAR	-40 to 150	27200
UCC27200DRMT	Obsolete	Production	VSON (DRM)   8	-	-	Call TI	Call TI	-40 to 140	27200
UCC27201D	Obsolete	Production	SOIC (D)   8	-	-	Call TI	Call TI	-40 to 140	27201
UCC27201DDA	Obsolete	Production	SO PowerPAD (DDA)   8	-	-	Call TI	Call TI	-40 to 140	27201
UCC27201DDAR	Active	Production	SO PowerPAD (DDA)   8	2500   LARGE T&R	Yes	NIPDAU   NIPDAUAG	Level-1-260C-UNLIM	-40 to 150	27201
UCC27201DDAR.A	Active	Production	SO PowerPAD (DDA)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27201
UCC27201DDAR.B	Active	Production	SO PowerPAD (DDA)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27201
UCC27201DR	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27201
UCC27201DR.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27201



-40 to 150

-40 to 140

Level-1-260C-UNLIM

Call TI

14-Oct-2025

27201

27201



UCC27201DRMRG4.B

UCC27201DRMT

www.ti.com

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	<b>RoHS</b> (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
UCC27201DR.B	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27201
UCC27201DRG4	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27201
UCC27201DRG4.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27201
UCC27201DRG4.B	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27201
UCC27201DRMR	Active	Production	VSON (DRM)   8	3000   LARGE T&R	Yes	Call TI   Nipdauag   Nipdau	Level-1-260C-UNLIM	-40 to 150	27201
UCC27201DRMR.A	Active	Production	VSON (DRM)   8	3000   LARGE T&R	Yes	Call TI	Level-1-260C-UNLIM	-40 to 150	27201
UCC27201DRMR.B	Active	Production	VSON (DRM)   8	3000   LARGE T&R	Yes	Call TI	Level-1-260C-UNLIM	-40 to 150	27201
UCC27201DRMRG4	Active	Production	VSON (DRM)   8	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27201
UCC27201DRMRG4.A	Active	Production	VSON (DRM)   8	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 150	27201

Active

Obsolete

Yes

NIPDAU

Call TI

3000 | LARGE T&R

Production

Production

VSON (DRM) | 8

VSON (DRM) | 8

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

## PACKAGE OPTION ADDENDUM

www.ti.com 14-Oct-2025

and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## OTHER QUALIFIED VERSIONS OF UCC27200:

Automotive : UCC27200-Q1

NOTE: Qualified Version Definitions:

Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects